MA2Z748

Silicon epitaxial planar type

For super high speed switching For small current rectification

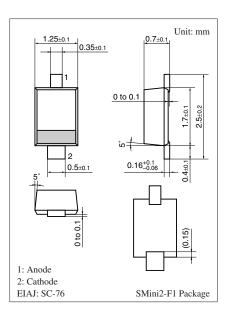
■ Features

- Low V_F type of MA3X720
- Low forward voltage V_F and good rectification efficiency
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}

■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | Symbol | Rating | Unit |
|---|--------------------|-------------|------|
| Reverse voltage | V _R | 20 | V |
| Repetitive peak reverse voltage | V _{RRM} | 20 | V |
| Forward current (Average) | I _{F(AV)} | 300 | mA |
| Non-repetitive peak forward surge current * | I _{FSM} | 3 | A |
| Junction temperature | T _j | 125 | °C |
| Storage temperature | T _{stg} | -55 to +125 | °C |

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



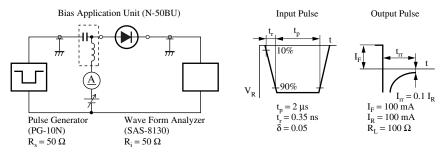
Marking Symbol: 2K

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

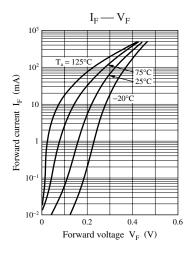
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|-------------------------|------------------|--------------------------------------|-----|-----|-----|------|
| Forward voltage | V_{F} | $I_F = 300 \text{ mA}$ | | | 0.4 | V |
| Reverse current | I_R | $V_R = 10 \text{ V}$ | | | 30 | μΑ |
| Terminal capacitance | C _t | $V_R = 0 V, f = 1 MHz$ | | 60 | | pF |
| Reverse recovery time * | t _{rr} | $I_F = I_R = 100 \text{ mA}$ | | 5 | | ns |
| | | $I_{rr} = 0.1 I_R, R_L = 100 \Omega$ | | | | |

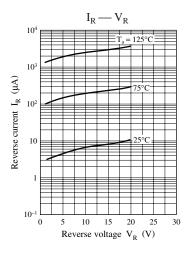
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

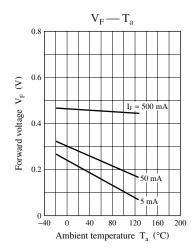
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 400 MHz.
- 4.*: t_{rr} measurement circuit

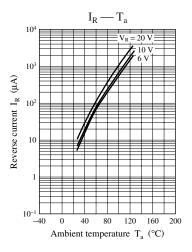


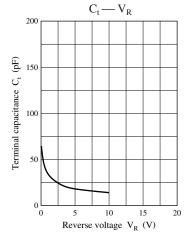
Panasonic

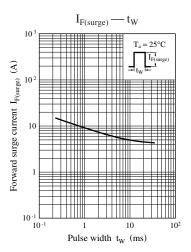












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